

CHIP TESTING WITHIN A MULTI-CHIP SEMICONDUCTOR PACKAGE

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ABSTRACT OF THE INVENTION

5 A system and method is provided for testing a secondary
chip housed within a multi-chip packaged semiconductor device.
The packaged semiconductor device includes a secondary chip and
a primary chip, with the secondary chip communicating with the
primary chip through signal drivers. The secondary chip also
10 includes at least one test signal driver connected to the signal
drivers and to certain external connectors that may be shared
with the primary chip. The test signal drivers provide testing
of the secondary chip using standard integrated circuit test
equipment while the secondary chip is contained within the
15 packaged semiconductor device.